



## Ultra-low Power Bluetooth and LE Audio Platform

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The BES2600Z is an ultra-low power Bluetooth audio SoC. The platform incorporates a high performance CPU subsystem comprising a dual-core STAR-MC1 with a BECO NPU, a BES proprietary coprocessor for advance signal processing and NN workloads, a sensor hub subsystem comprising a STAR-MC1 processor, RAM/ROM, serial flash for software features and product customization, as well as a variety of interfaces.

The platform integrates a dual-mode Bluetooth 5.3 subsystem for both Bluetooth classic and LE audio, and an audio codec subsystem supporting voice activity detection. The highly integrated solution is optimized through the use of IBRT technology, a BES patented sniffing technique that incorpo Td(m)04B or6d(wl)1.4 (p)-116 (r)0.7(d)-0.9(Ec)-4.1 (r)0.7(r)0.7(o)01.

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CPU Subsystem	STAR-MC1
Sensor Hub Subsystem	STAR-MC1
Memory and Storage	Shared 1.2 MB SRAM
	Flash in package
	boot ROM
Bluetooth Subsystem	Dual-mode BT 5.3 with LE audio
Audio & Voice Features	1x DAC
	4x ADCs
Peripheral Interfaces	GPADC/SPI/I2C/UART/I2S/TDM/SPDIF/DMIC/GPIO.....
Package	108-ball BGA

\* The content in the table is subject to change without notice.